



MMIC Handling and Die Attach Recommendations

Summary

- Do not contact the die surface, handle from the edges to avoid contacting airbridges
- ActivCirk recommends epoxy die attach
 - Epoxy die attach requires a thin layer of epoxy; no more than 20 um thick
 - Solder die attach (<300°C for <1 minute) may also be used with care
- ActivCirk recommends 25 um wide gold ribbon/wire for RF pads and DC pads

Handling MMICs

Electrostatic Discharge (ESD)

MMICs may be destroyed or damaged by electrostatic discharge; ESD damage is often not obvious at the time of exposure. Proper ESD precautions must be employed when handling MMICs.

Grounding is critical for floors and all work surfaces, bonding and handling equipment, and other test or assembly machinery. Operators should always wear wrist or foot ground straps. ESD test equipment should be available to ensure proper ESD grounding always.

Handle Die from Edges

During MMIC die attach assembly, handle the die along the edge; do not contact the surface of the die. Use tweezers or a vacuum collet sized to contact the edges of the die, so that plated air bridges are not damaged or deformed during handling and assembly.

MMIC Die Attach

Two methods are commonly used to attach MMICs to microcircuit packages or pedestals: solder and epoxy. Solder (usually eutectic) has historically been the only method of MMIC die attach. In recent years, there have been significant advances in epoxy technology for this application. Thus, epoxy die attach has become the preferred die attach method in most MMIC applications.

Epoxy Die Attach

Advantages of epoxy die attach include production efficiency, reduced rework, increased placement accuracy, and less sensitivity to thermal expansion mismatch of the MMIC to its mounting substrate.

One potential disadvantage of epoxy is the relatively high thermal resistance compared to solder. This is largely avoided when considering the very thin layer of epoxy required, which results in a smaller

temperature gradient through the die attach layer. Die attach epoxies are available as a pre-form or in a mixing dispenser. The major consideration when using epoxies is the final die attach layer thickness. An accepted target is one-fourth to three-fourths of a mil thick that may need to be adjusted for thermal stress considerations. The thin layer maintains a low thermal gradient through the epoxy and a low inductance between the MMIC backside and ground. Thick layers of epoxy can present enough inductance to the RF ground circuit to introduce oscillation or other performance issues. Too much or too little epoxy can cause problems: the epoxy fillet around the die should be no more than half-way up the side of the 50 um thick MMIC. Too little epoxy may lead to voids (discussed in the solder section), too much epoxy may lead to stringers and shorts to the front-side metal.

Solder Die Attach

Although solder die attach is being replaced in many applications by modern die attach epoxies, there are applications where solder die attach may be preferred. For example, high power dissipation MMICs require optimum thermal dissipation and may benefit from solder die attach. The high operating temperatures of these devices can sometimes soften epoxies, resulting in performance and reliability issues. Gold-Tin (80/20) eutectic solder is the most common alloy used for MMIC solder die attach. Pre-forms are often used; they are originally smaller than the MMIC, but result in complete coverage of the backside when attached. The pre-form size is determined experimentally. Various methods are used to apply pressure and a scrubbing motion to the MMIC to embed the die into the solder.

Solder die attach results in a more rigid connection to the mounting surface compared with epoxy. Selection of the die attach material should consider the differences in thermal expansion coefficients (CTE) between the die and the mounting surface. MMICs will crack if there are large differences in expansion between the materials. Often MMICs are mounted on pedestals which are made of kovar, molybdenum, or silicon, because these materials closely match the expansion of GaAs, GaN or InP ($\sim 7\text{ppm}/^\circ\text{C}$), and are good thermal conductors.

Another important consideration when using solder die attach is the possibility of solder voids. A void, or air bubble, can reduce device reliability by critically reducing the thermal conductivity. If voids are located directly under FET fingers, heat will not be efficiently dissipated, and channel temperatures will increase until the device prematurely fails. Correctly sized pre-forms can reduce voids

Die must not be exposed to temperatures $>300^\circ\text{C}$ for more than 1 minute.

Wire Bonding

Thermosonic wire bonding is the recommended method of attaching wires to MMIC bond pads. Two thermosonic bonding tools are commonly used: wedge and capillary. For



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optimal bonds, the combination of bonding force, time, and temperature is critical. Manufacturers of wire bonding equipment provide technical information for a good starting point for successful wire bonding to MMIC bond pads. ActivCirk can provide mechanical die for bonding practice. Ensure the bonding tool is grounded. Be very careful to not touch the surface of the MMIC during the bonding procedure (bond pads excluded, of course). Bond first to the die, then to the package. Take care to observe the recommended assembly diagrams provided for each ActivCirk MMIC, and be sure to bond to the appropriate pads. ActivCirk typically recommends 25 um soft gold bondwire, used with a rear-feed wedge bond tool.

MMIC Performance

MMIC performance can often be affected by die attach and MMIC interface methods.

ActivCirk recommendations for MMIC high performance:

1. Use a pedestal under the die to bring the face of the die level with the RF input and output transmission line (to shorten wirebonds)
2. Use multiple short wirebonds or ribbons on the RF input and output pads for a low inductance connection to the MMIC.
3. Consider adding shunt capacitance (stubs) on the far end of the wire bond. Typically there is a microstrip line on a substrate which can be patterned with shunt stubs that can be easily modeled on a circuit simulator.
4. Bond as close to the edges of the input and output lines that a reliable connection will allow.